

**Industry's highest  
Tg 160°C**

**Compatible with the package  
size of 25 mm square or more**

**Pot life is long 3 days**

**Applications  
IC Package/Automotive**

Mount reinforcement of semiconductor packages and electronic parts for automotive camera modules, millimeter-wave radar modules, ECU.

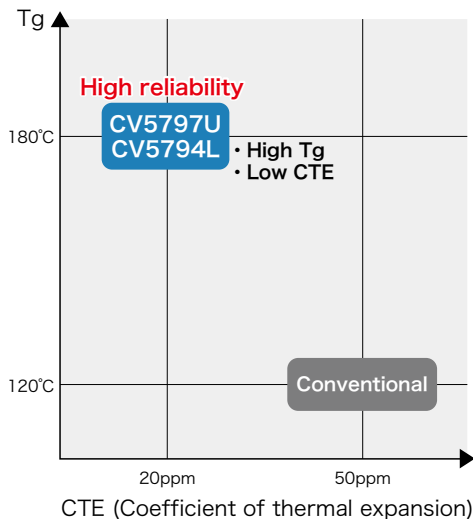
## LEXCM<sup>DF</sup>

### CV5797 series CV5794 series

#### High heat resistance secondary mounting sidefill/underfill materials

Achieves automotive grade assembly-level reliability requirements with the industry's highest heat resistance and low CTE. Package periphery (edge and corner) reinforcement materials available. RoHS compliant.

#### Concept



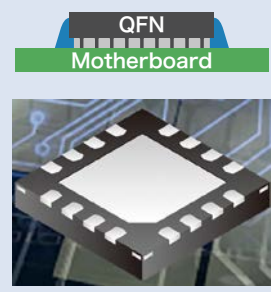
#### Reinforcement type (Applicable IC package)

**Sidefill**

**For large-size package**  
(e.g. 25 mm square or more)



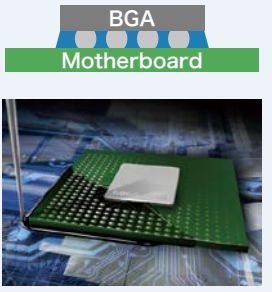
BGA  
Motherboard



QFN  
Motherboard

**Underfill**

**For small and medium size package**  
(e.g. 20 mm square or less)

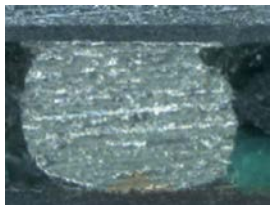


BGA  
Motherboard

#### Correspond to temperature cycle test under automotive environment

CV5797U/ CV5794L

Conventional



Item	CV5797U	Conventional
Temperature cycling test (TCT) -55°C⇔125°C 30min	6000 cycles Pass	3000 cycles Pass

#### General properties

Item	Unit	CV5797U Sidefill (Corner glue)	CV5794L Underfill
Glass transition temp. (Tg)	°C	160	160
C.T.E.1	ppm/°C	13	21
Flexural modulus (25°C)	GPa	20	15
Storage condition	—	-20°C/ 6months	

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry CV5797

Panasonic Industry Co., Ltd. Electronic Materials Business Division

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